

*Conclude
§ 1*

2. (Twice Amended) The semiconductor device according to claim 1, further comprising an interconnection terminal electrically connected to the active surface of the semiconductor chip and having an exposed portion exposed to the outside of the protective resin, the interconnection terminal being joined to the active surface of the semiconductor chip and to a surface of the board that is facing to the semiconductor chip, the external terminal being electrically connected to the active surface of the semiconductor chip via the interconnection terminal.

§ 2

7. (Thrice Amended) A semiconductor device, comprising:
a board;
a semiconductor chip having an active surface and an inactive surface which is a surface on the opposite side of the active surface, the semiconductor chip being joined to the board in a state where the active surface thereof is facing to the board and the inactive surface thereof is exposed; and
an external connecting terminal joined to a surface of the board that is facing away from the semiconductor chip, the external connecting terminal being electrically connected to the active surface of the semiconductor chip.

§ 3

18. (Amended) A semiconductor device, comprising:
a semiconductor chip having an active surface and an inactive surface disposed opposite the active surface;
a board on which the semiconductor chip is mounted;
an external connecting terminal joined to a surface of the board that is facing away from the semiconductor chip, the external connecting terminal being electrically connected to the active surface of the semiconductor chip and projecting therefrom;
an underfill resin surrounding the external connecting terminal to form an outer peripheral underfill resin surface and covering at least a portion of the active surface; and
a protective a resin covering a sidewall of the semiconductor chip and the